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Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims of the application.

Listing of Claims:

Claims 1 to 4 and 9 to 10 have been previously withdrawn.

5. (Currently Amended) A curable clay adhesive composition comprising:

a) a curable medium comprising at least one ethylenically unsaturated compound selected from the group consisting of ethylenically unsaturated monomer and ethylenically unsaturated oligomer, and mixtures thereof; and

b) from 0.5 to 20 weight %, based on a total weight of said curable clay adhesive composition; of exfoliated clay platelets dispersed in said curable medium;

wherein said curable clay adhesive composition is substantially free of photoinitiator.

6. (Currently Amended) The curable adhesive composition according to claim 5 wherein said curable medium comprises a weight ratio of said ethylenically unsaturated monomer to said ethylenically unsaturated oligomer in the range of 10:1 to 1:2.

7. (Currently Amended) A curable clay adhesive composition comprising:

a) a curable medium comprising:

i) from 40 to 98.5 weight % of at least one ethylenically unsaturated compound selected from the group consisting of ethylenically unsaturated monomer and ethylenically unsaturated oligomer, and mixtures thereof; and

ii) from 1 to 40 weight % soluble polymer; and

b) from 0.5 to 20 weight % exfoliated clay platelets dispersed in said curable medium;

wherein all weight % are based on total weight of said curable clay adhesive composition.

8. (Currently Amended I) The curable adhesive composition according to claim 7 wherein said curable medium comprises a weight ratio of said ethylenically unsaturated monomer to said ethylenically unsaturated oligomer in the range of 10:1 to 1:2.
11. (Currently Amended) The curable clay adhesive composition of claim 5 further comprising less than 5 weight %, based on the weight of the curable clay adhesive composition, solvent.
12. (Currently Amended) The curable clay adhesive composition of claim 5 wherein said curable medium comprises from 40 to 99.5 weight %, based on the weight of the curable clay adhesive composition, ethylenically unsaturated compound.
13. (Currently Amended) The curable clay adhesive composition of claim 5 wherein said curable medium comprises from 45 to 85 weight %, based on the weight of the curable clay adhesive composition, ethylenically unsaturated compound.
14. (Currently Amended) The curable clay adhesive composition of claim 5 wherein said curable medium comprises from 50 to 80 weight %, based on the weight of the curable clay adhesive composition, ethylenically unsaturated compound.
15. (Currently Amended) The curable clay adhesive composition of claim 5 wherein said curable medium further comprises at least one soluble polymer.
16. (Currently Amended) The curable clay adhesive composition of claim 5 wherein said curable medium further comprises 0 to 40 weight %, based on the weight of the curable clay adhesive composition, of at least one soluble polymer.
17. (Currently Amended) The curable clay adhesive composition of claim 5 wherein said curable medium further comprises 2 to 30 weight %, based on the weight of the curable clay adhesive composition, of at least one soluble polymer.

18. (Currently Amended) The curable clay adhesive composition of claim 7 further comprising less than 5 weight %, based on the weight of the curable clay adhesive composition, solvent.
19. (Currently Amended) The curable clay adhesive composition of claim 7 wherein said curable medium further comprises two or more soluble polymers.
20. (Currently Amended) The curable clay adhesive composition of claim 7 wherein said curable medium further comprises 1 to 40 weight %, based on the weight of the curable clay adhesive composition, of two or more polymers.
21. (Currently Amended) The curable clay adhesive composition of claim 7 wherein said curable medium further comprises 2 to 30 weight %, based on the weight of the curable clay adhesive composition, of at least one soluble polymer.
22. (Currently Amended) The curable clay adhesive composition of claim 7 wherein said curable medium comprises from 45 to 85 weight %, based on the weight of the curable clay adhesive composition, ethylenically unsaturated compound.
23. (Currently Amended) The curable clay adhesive composition of claim 7 wherein said curable medium comprises from 50 to 80 weight %, based on the weight of the curable clay adhesive composition, ethylenically unsaturated compound.